

Course Information					
Course Code	MT493	* Credit Hours	32	* Credits	2
* Course Name	Materials and Reliability of Electronic Packaging				
(Course Type)					
Audience					
(Language of Instruction)					
* School					
Prerequisite					
Instructor			(Course Webpage)		
* Description					
* Description	<p>This course is designed for students of science and engineering, especially for those majoring Intelligent Chip Fabrication and Electronic Materials. It introduces the microelectronic structure, principles of microelectronic fabrication, key manufacturing processes and types of electronic packaging material differed by functions, fundamentals, performance requirements. Challenges and development trend in industries are also demonstrated. After learning the course, students can know and master the Principles of Microelectronic Fabrication, processing and electronic packaging materials comprehensively, and widen knowledge and strengthen innovative ability in high level microelectronic fabrication.</p> <p>Assessment Tools: paper</p>				

course syllabus

<p>* (Learning Outcomes)</p>	<p>1. 3.1 2. TSV 3.</p>	<p>2.3 2.4 2.3 2.4 3.2 7.1</p>	<p>2.3 2.4</p>
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<p>* relationship between learning outcomes and graduation requirements</p>				
	2	2.3	1 2	
		2.4	1 2	
	3 /	3.1	1	
		3.2	2	
7	7.1	3		

<p>* (Class Schedule &Requirements)</p>	Content	Hours	Format	Instructor
		2		
		4		
		4		
		2		
	PCB	2		
		4		
		2		
		2		

		4		
		4		
		2		
* (Grading)		70%+		30%

* 1.
 (Textbooks & Other
 Materials)